

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. - 8. (Cancelled)

9. (Currently Amended) A semiconductor device mounting structure including a semiconductor device having an electrode and a substrate having a wiring terminal that is conductively connected to the electrode, wherein

~~a width of one of the electrode and the wiring terminal is smaller than a width of the other of the electrode; and the wiring terminal, and~~

a recessed portion formed in a center portion of the electrode, the recessed portion is constituted by a dimension corresponding to the width of the wiring terminal; and

the one of the electrode and the wiring terminal is embedded in a surface of the other of the electrode and the wiring terminal.

10. (Original) The semiconductor device mounting structure of claim 9, wherein a cross-sectional shape of the one of the electrode and the wiring terminal decreases towards the other of the electrode and the wiring terminal.

11. (Original) The semiconductor device mounting structure of claim 9, wherein the one of the electrode and the wiring terminal further comprises a material having a

higher hardness than a hardness of the other of the electrode and the wiring terminal.

12. (Original) The semiconductor device mounting structure of claim 9, wherein the electrode and the wiring terminal both include a plurality of members, and widths of all of the one of the electrode and wiring terminals which are conductively connected to the other of the electrode and the wiring terminal are substantially the same.

13. - 14. (Cancelled)

15. (Currently Amended) An electro-optical device comprising:
an electro-optical panel retaining an electro-optical substance;
a wiring substrate including a wiring terminal conductively connected to the electro-optical panel; and
a semiconductor device including an electrode conductively connected to the wiring terminal; wherein:
a width of the wiring terminal is smaller than a width of the electrode; ~~and~~
a recessed portion formed in a center portion of the electrode, the recessed portion is constituted by a dimension corresponding to the width of the wiring terminal;
and
the wiring terminal is embedded in a surface of the electrode.

16. - 23. (Cancelled)